

Product	LED
Package	LAMP
Series	SLI-560 * T

1.試験結果(Test Result)

Test Items Reference STD Test Condition (pcs) (pcs) 平田耐熱 JESD22-B106D 260±5°C OP b7)-平田槽に 端子根元のmまで10±1秒浸漬 222 0 Solder Heat Resistance for Reflow Soldering JESD22-B102E D'>ズネ7ラ7/X155±1秒浸漬し、245±5°C0 Pb7)-平田槽で製品裏面を3±0.5秒浸漬 Immerse into rosin flux for 5±1sec.and the device for 3±0.5sec into Pb-free solder bath at 245±5°C 222 0 *1 Solderbility JEITA ED-4701 高さ:75cm 楓板上:3回 H=75cm Maple Boad:3 times 22 0 *1 Free Drop A-124 H=75cm Maple Boad:3 times 22 0 4 版動 JEITA ED-4701 100~2000Hz 98.1m/S ² X.Y.Z0A5方向 2時間 22 0 描子引張強度 JESD22-B105D 荷重:10N(1Kgf) 30秒 22 0 22 0 Lead Pull Test JESD22-A104E Ta=Tstg Min.*C(30min).~ Tstg Max.*C(30min).100cycle 22 0 22 0 編子引振れ行強度 JESD22-A104E Ta=Tstg Min.*5°C 1000hrs 22 0 編示引振れ行強度 JESD2-A104E Ta=Tstg Min.*5°C/-0°C 1000hrs 22 0 0 高温な置 JESD22-A104E <td< th=""><th>1.武豪和朱(Test 1 試験項目</th><th>参考規格</th><th>試験条件</th><th>n</th><th>Pn</th><th>٦</th></td<>	1.武豪和朱(Test 1 試験項目	参考規格	試験条件	n	Pn	٦
単田耐熱 JESD22-B106D 260±5°CのPb7J-半田槽に 端子根元のmmまで10±1秒浸漬 22 0 Solder Heat Resistance or Reflow Soldering JESD22-B102E ロジン系フラックスIC5±1秒浸漬し、245±5°Cの Pb7J-半田槽で製品裏面を3±0.5秒浸漬 Immerse into rosin flux for 5±1sec, and the device for 3±0.5sec into Pb-free solder bath at 245±5°C 22 0 *1 Solderbility JEITA ED-4701 高さ:75cm 楓板上:3回 H=75cm Maple Boad: 3 times 22 0 *1 Wibration A-124 H=75cm Maple Boad: 3 times 22 0 *1 Wibration A-124 H=75cm Maple Boad: 3 times 22 0 *1 Wibration A-124 H=75cm Maple Boad: 3 times 22 0 22 0 ##3 明 JEITA ED-4701 100~2000Hz 98.1m/S ² Lead Pull Test 22 0 22 0 22 0 ##3 明 JEITA ED-4701 A-124 H=75cm Maple Boad: 3 times 22 0 22 0 22 0 20 20 20 20 20 20 20 20 20 22 0 22 0 22 0 22 0 22 <td></td> <td></td> <td></td> <td></td> <td></td> <td></td>						
Solder Heat Resistance for Reflow Soldering 端子根元0mmまで10±1秒浸漬 Immerse the reverse side of the device on the surface of Pb-free solder bath at 260±5°C for 10±1sec 22 0 W=H0ftE Solderbility JESD22-B102E D'>系75707Al:5±1PD浸漬L, 245±5°C 22 0 *1 Solderbility JESD22-B102E D'>系75707Al:5±1PD浸漬L, 245±5°C 22 0 *1 Solderbility JEITA ED-4701 Table Solder bath at 245±5°C 22 0 *1 Ram JEITA ED-4701 Table Solder bath at 245±5°C 22 0 *1 Kasth JEITA ED-4701 Table Solder bath at 245±5°C 22 0 *1 Kasth JEITA ED-4701 Table Solder bath at 245±5°C 22 0 22 0 Kasth JEITA ED-4701 Table Solder bath Mayle Boad : 3 times 22 0 22 0 Kasth JESD22-B105D Table Ead Pull Test JESD22-B105D Table Site in 0N(1Kgf) 30Sec 22 0 0 Lead Pull Test JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 0 22 0				(pcs)	(pcs)	-
Solder Heat Resistance for Reflow Soldering Immerse the reverse side of the device on the surface of Pb-free solder bath at 260±5°C for 10±1sec 22 0 ¥田村性 Solderbilty JESD22-B102E D*ン茶7ラ7)7λ[25±1秒浸漬[,, 245±5°C0) Pb7]-#田槽で製品裏面を3±0.5秒浸漬] Immerse into rosin flux for 5±1sec,and the device for 3±0.5sec into Pb-free solder bath at 245±5°C 22 0 落下 Free Drop A-124 H=75cm Maple Boad : 3 times 22 0 振動 JEITA ED-4701 A-124 100~2000Hz 98.1m/S ² Zhours each on each direction of X,Y,Z 22 0 端子引張強度 JESD22-B105D 荷重:10N(1Kgf) 30秒 Load:10N(1Kgf) 30Sec 22 0 端子引張強度 JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JESD22-A103E Ta=Tstg Min.±5°C 1000hrs 22 0 高温放置 JEITA ED-4701 B-121 Ta=Tstg Min.±5°C 1000hrs 22 0	十日则怒	JE3D22-B100D				
for Reflow Soldering of Pb-free solder bath at 260±5°C for 10±1sec ************************************	Saldar Haat Basistanaa			22	0	
平田付性 JESD22-B102E ロジン系フラックスに5±1秒浸漬し、245±5°Cの 22 0 *1 Solderbility JESD22-B102E ロジン系フラックスに5±11を2,and the device for 3±0.58ec into Pb-free solder bath at 245±5°C 22 0 *1 Solderbility JEITA ED-4701 高さ:75cm 楓板上:3回 22 0 *1 Free Drop A-124 H=75cm Maple Boad:3 times 22 0 22 0 振動 JEITA ED-4701 100~2000Hz 98.1m/S ² X.Y.Zの各方向 2時間 22 0 22 0 K振動 JESD22-B105D 荷重:10N(1Kgf) 30秒 22 0 22 0 Wibration JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 0 Lead Pull Test JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 0 Lead Bend Test JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 0 Bigh Temperature JEITA ED-4701 B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 Strage JEITA ED-4701 B-121 Ta=85±2°C 1000hrs 22 0 0 Krage JEITA ED-4701						
Solderbility Pb7/Jー半田槽で製品裏面を3±0.5秒浸漬 Immerse into rosin flux for 5±1sec,and the device for 3±0.5sec into Pb-free solder bath at 245±5°C 22 0 *1 落下 Free Drop JEITA ED-4701 高さ:75cm 楓板上:3回 H=75cm Maple Boad:3 times 22 0 *1 版動 JEITA ED-4701 100~2000Hz 98.1m/S ² 22 0 *1 Wibration A-121 100~2000Hz 98.1m/S ² 22 0 22 0 Wibration A-121 100~2000Hz 98.1m/S ² 22 0 0 22 0 K#子引張強度 JESD22-B105D 荷重:10N(1Kgf) 30秒 Lead Pull Test 22 0	<u> </u>					-
Immerse into rosin flux for 5±1sec,and the device for 3±0.5sec into Pb-free solder bath at 245±5°C 22 0 *1 落下 Free Drop A-124 H=75cm Maple Boad : 3 times H=75cm Maple Boad : 3 times 22 0 振動 JEITA ED-4701 高さ: 75cm 楓板上: 3回 H=75cm Maple Boad : 3 times 22 0 振動 JEITA ED-4701 100~2000Hz 98.1m/S ² 2hours each on each direction of X,Y,Z 22 0 端子引張強度 JESD22-B105D 荷重: 10N(1Kgf) 30秒 Load: 10N(1Kgf) 30sec 22 0 端子折曲/f 強度 JESD22-B105D 荷重: 1.25N(0.125Kgf) 0° ~90° ~0° ~-90° ~0° Load: 1.25N(0.125Kgf) 0° ~90° ~0° ~90° ~0° 22 0 温度サ/J/h JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 Frage JESD22-A104E Ta=Tstg Min.±5°C 1000hrs 22 0 Migh Temperature JESD22-A104E Ta=Tstg Min.±5°C 1000hrs 22 0 G温度が置 JESD22-A119A Ta		JESD22-B102E				
for 3±0.5sec into Pb-free solder bath at 245±5°C クローク 落下 JEITA ED-4701 高さ:75cm 楓板上:3回 H=75cm Maple Boad:3 times 22 0 振動 JEITA ED-4701 A-124 100~2000Hz 98.1m/S ² X,Y,Zの各方向 2時間 100~2000Hz 98.1m/S ² 2hours each on each direction of X,Y,Z 22 0 端子引張強度 JESD22-B105D 荷重:10N(1Kgf) 30秒 Load:10N(1Kgf) 30sec 22 0 上ead Pull Test JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~-90° ~0° 22 0 温度サイ介ル JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~-90° ~0° 22 0 温度サイ介ル JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 Frage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Malb JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 0 Kange	Solderbility			22	0	*1
Free Drop A-124 H=75cm Maple Boad : 3 times 222 0 振動 JEITA ED-4701 100~2000Hz 98.1m/S ² X,Y,Zの各方向 2時間 22 0 Vibration A-121 100~2000Hz 98.1m/S ² X,Y,Zの各方向 2時間 22 0 Wibration A-121 100~2000Hz 98.1m/S ² 22 0 Wibration A-121 100~2000Hz 98.1m/S ² 22 0 Wibration JESD22-B105D 荷重:10N(1Kgf) 30秒 22 0 Lead Pull Test JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 Lead Bend Test JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 Image Job After Strage JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 Righ Temperature JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 Righ Temperature JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 Righ Temperature JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Krage JESD22-A119A			,			
Free Drop A-124 H=75cm Maple Boad : 3 times D 振動 JEITA ED-4701 100~2000Hz 98.1m/S ² X,Y,Zの各方向 2時間 100~2000Hz 98.1m/S ² 22 0 端子引張強度 JESD22-B105D 荷重 : 10N(1Kgf) 30秒 Load : 10N(1Kgf) 30% 22 0 端子引張強度 JESD22-B105D 荷重 : 1.25N(0.125Kgf) 0° ~90° ~0° ~-90° ~0° 22 0 端子折曲げ強度 JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 温度サイカル JESD22-A104E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 Fingh Temperature B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 Kabd JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Galabat JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 High Temperature B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 Mumidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Maghe phon JESD22-A119A Ta=25±5°C IF=IFMAX 1000h		JEITA ED-4701	 高さ:75cm 楓板上:3回			
Vibration A-121 100~2000Hz 98.1m/S ² 2hours each on each direction of X,Y,Z 22 0 端子引張強度 Lead Pull Test JESD22-B105D 荷重:10N(1Kgf) 30秒 Load:10N(1Kgf) 30sec 22 0 端子折曲げ強度 Lead Bend Test JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 温度サイクル Thermal Cycle JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JEITA ED-4701 B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 K温放置 JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Min Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Maakab JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 min High Temperature JESD22-A119A Ta=Tstg Min.±5°C IF=IFMAX 1000hrs 22 0 Mmaakab JESD22-A108D Ta=25±5°C IF=IFMAX 10	Free Drop	A-124	H=75cm Maple Boad : 3 times	22	0	
Vibration A-121 100~2000Hz 98.1m/S ² 2hours each on each direction of X,Y,Z 22 0 端子引張強度 Lead Pull Test JESD22-B105D 荷重:10N(1Kgf) 30秒 Load:10N(1Kgf) 30sec 22 0 端子折曲げ強度 Lead Bend Test JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 温度サイクル Thermal Cycle JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 高温放置 JEITA ED-4701 B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 K温放置 JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Min Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Maakab JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 min High Temperature JESD22-A119A Ta=Tstg Min.±5°C IF=IFMAX 1000hrs 22 0 Mmaakab JESD22-A108D Ta=25±5°C IF=IFMAX 10	振動	JEITA ED-4701	100~2000Hz 98.1m/S ² X,Y,Zの各方向 2時間			
端子引張強度 JESD22-B105D 荷重:10N(1Kgf) 30秒 22 0 Lead Pull Test JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~-90° ~0° 22 0 端子折曲げ強度 JESD22-B105D 荷重:1.25N(0.125Kgf) 0° ~90° ~0° ~-90° ~0° 22 0 Lead Bend Test JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 温度サイクル JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 Strage JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 Migh Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Migh Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 22 0 Migh Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Might Fape JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	Vibration	A-121		22	0	
Lead Pull Test Load: 10N(1Kgf) 30sec 22 0 端子折曲げ強度 JESD22-B105D 荷重: 1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 Lead Bend Test Load: 1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° 22 0 温度サイクル JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 Strage JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 Migh Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 低温放置 JESD22-A119A Ta=85±2°C 85±5%RH 240hrs 22 0 migh Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Max Ta=Stag Min.±5°C 1000hrs 22 0 0			2hours each on each direction of X,Y,Z			
Lead Pull Test Load: 10N(1Kgf) 30sec 1	端子引張強度	JESD22-B105D	荷重:10N(1Kgf) 30秒	0.0	0	
Lead Bend Test Load: 1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° ~20° ~0° 22 0 温度サイル JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 Strage 22 0 0 22 0 高温高湿放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 High Temperature B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 Kalb JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Migh Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Mc温放置 JESD22-A119A Ta=Tstg Min.±5°C IF=IFMAX 1000hrs 22 0 0	Lead Pull Test			22	0	
Lead Bend Test Load: 1.25N(0.125Kgf) 0° ~90° ~0° ~0° ~0° ~0° 1 1 温度サイクル JESD22-A104E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle 22 0 高温放置 JESD22-A103E Ta=Tstg Max.+5°C/-0°C 1000hrs 22 0 Strage 22 0 22 0 高温高湿放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 High Temperature B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 K温放置 JESD22-A119A Ta=85±2°C 85±5%RH 240hrs 22 0 K温放置 JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Muidty Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Strage JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	端子折曲げ強度	JESD22-B105D	荷重:1.25N(0.125Kgf) 0°~90°~0°~-90°~0°	22	0	
Thermal Cycle220高温放置JESD22-A103ETa=Tstg Max.+5°C/-0°C 1000hrs220High TemperatureJEITA ED-4701Ta=85±2°C 85±5%RH 240hrs220高温高湿放置JEITA ED-4701Ta=85±2°C 85±5%RH 240hrs220High TemperatureB-121Ta=85±2°C 1000hrs220Migh Humidity StrageJESD22-A119ATa=Tstg Min.±5°C 1000hrs220低温放置JESD22-A119ATa=Tstg Min.±5°C 1000hrs220StrageJESD22-A108DTa=25±5°C IF=IFMAX 1000hrs220	Lead Bend Test		Load: 1.25N(0.125Kgf) $0^{\circ} \sim 90^{\circ} \sim 0^{\circ} \sim -90^{\circ} \sim 0^{\circ}$	22	0	
Thermal CycleImage: Constraint of the systemImage:	温度サイクル	JESD22-A104E	Ta=Tstg Min.°C(30min.) ~ Tstg Max.°C(30min.)100cycle	22	0	
High Temperature StrageJEITA ED-4701 B-121Ta=85±2°C 85±5%RH 240hrs220Image: B-121Image: B-121Image: B-121Image: B-121Image: B-121Image: B-121High Humidity StrageJESD22-A119A StrageTa=Tstg Min.±5°C 1000hrs220Image: B-121Image: B-121I	Thermal Cycle			22	0	
Strage JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 高温高湿放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 High Temperature B-121 Ta=Tstg Min.±5°C 1000hrs 22 0 低温放置 JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Strage JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	高温放置	JESD22-A103E	Ta=Tstg Max.+5°C/-0°C 1000hrs			
高温高湿放置 JEITA ED-4701 Ta=85±2°C 85±5%RH 240hrs 22 0 High Temperature B-121 Ta=85±2°C 85±5%RH 240hrs 22 0 High Humidity Strage JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Low Temperature JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Strage JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	High Temperature			22	0	
High Temperature High Humidity StrageB-121220High Humidity StrageJESD22-A119A Low Temperature StrageJESD22-A119A Low Temperature StrageTa=Tstg Min.±5°C 1000hrs Low Temperature Strage220動作寿命JESD22-A108D JESD22-A108DTa=25±5°C IF=IFMAX 1000hrs Low Temperature Strage220	Strage					
High Humidity Strage	高温高湿放置	JEITA ED-4701	Ta=85±2°C 85±5%RH 240hrs			
低温放置 JESD22-A119A Ta=Tstg Min.±5°C 1000hrs 22 0 Low Temperature Strage 25±5°C IF=IFMAX 1000hrs 22 0	High Temperature	B-121		22	0	
Low Temperature 22 0 Strage JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	High Humidity Strage					
Strage JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	低温放置	JESD22-A119A	Ta=Tstg Min.±5°C 1000hrs			
動作寿命 JESD22-A108D Ta=25±5°C IF=IFMAX 1000hrs 22 0	Low Temperature			22	0	
	Strage					
Load Life ZZ 0	動作寿命	JESD22-A108D	Ta=25±5°C IF=IFMAX 1000hrs	22	0	
	Load Life			22	0	

2.測定項目及び故障判定基準(Failure Criteria)

測定項目	測定条件	故障判定基準
Items	Condition	Criteria
光度	20mA	初期値の60%
Luminous Intensity	2011A	60% of the initial value
順方向電圧	20mA	初期値に対する変化率±10%
Forward Voltage		Changing rate of $\pm 10\%$
逆方向電流	VR=VR Max.	規格最大値
Reverse Current	Reverse Current	
外観	目視	著しい変化のないこと
Physical	Visual Check	No outstanding change in physical

*1

 半田付性
 電極部の95%以上が半田で覆われていること

 Solderbility
 More than 95% of the electrode must be covered with solder.

 ※当データは、特定Lotの実力値であり保証値ではありません。

%This data is actual value from specific lot and is not guaranteed.

	Notes				
1)	The information contained herein is subject to change without notice.				
2)	Before you use our Products, please contact our sales representative and verify the latest specifica- tions :				
3)	Although ROHM is continuously working to improve product reliability and quality, semicon- ductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.				
4)	Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.				
5)	The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.				
6)	The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communi- cation, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.				
7)	The Products specified in this document are not designed to be radiation tolerant.				
8)	For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.				
9)	Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.				
10)	ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.				
11)	ROHM has used reasonable care to ensur the accuracy of the information contained in this document. However, ROHM does not warrants that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.				
12)	Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. For more details, including RoHS compatibility, please contact a ROHM sales office. ROHM shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.				
13)	When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.				
14)	This document, in part or in whole, may not be reprinted or reproduced without prior consent of ROHM.				



Thank you for your accessing to ROHM product informations. More detail product informations and catalogs are available, please contact us.

ROHM Customer Support System

http://www.rohm.com/contact/